



# PMEG3002AESF

30 V, 0.2 A low VF MEGA Schottky barrier rectifier

10 March 2017

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection in a DSN0603-2 (SOD962-2) leadless ultra small Chip-Scale Package (CSP).

## 2. Features and benefits

- Average forward current  $I_{F(AV)} \leq 0.2$  A
- Reverse voltage  $V_R \leq 30$  V
- Low forward voltage typ.  $V_F = 250$  mV
- Low reverse current typ.  $I_R = 4$   $\mu$ A
- Package height typ. 0.3 mm

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Ultra high speed switching
- LED backlight for mobile application

## 4. Quick reference data



Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 140$ °C; square wave	[1]	-	-	0.2	A
		$\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 147$ °C; square wave		-	-	0.2	A
$V_R$	reverse voltage	$T_j = 25$ °C		-	-	30	V
$V_F$	forward voltage	$I_F = 10$ mA; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; $T_j = 25$ °C		-	250	320	mV
$I_R$	reverse current	$V_R = 10$ V; $T_j = 25$ °C; pulsed		-	4	30	$\mu$ A
$t_{rr}$	reverse recovery time	$I_F = 500$ mA; $I_R = 500$ mA; $I_{R(meas)} = 100$ mA; $T_j = 25$ °C		-	1.37	-	ns

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 <p>Transparent top view DSN0603-2 (SOD962-2)</p>	 <p>1 2 sym001</p>
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG3002AESF	DSN0603-2	Leadless ultra small package; 2 terminals; body 0.6 x 0.3 x 0.3 mm	SOD962-2

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG3002AESF	L

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	30	V
$I_F$	forward current	$T_{sp} \leq 145\text{ °C}$ ; $\delta = 1$		-	0.28	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} \leq 140\text{ °C}$ ; square wave	[1]	-	0.2	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{sp} \leq 147\text{ °C}$ ; square wave		-	0.2	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$		-	1.5	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; square wave		-	4	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	405	mW
			[3]	-	660	mW

Symbol	Parameter	Conditions		Min	Max	Unit
			[1]	-	1200	mW
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-55	150	°C
$T_{stg}$	storage temperature			-65	150	°C

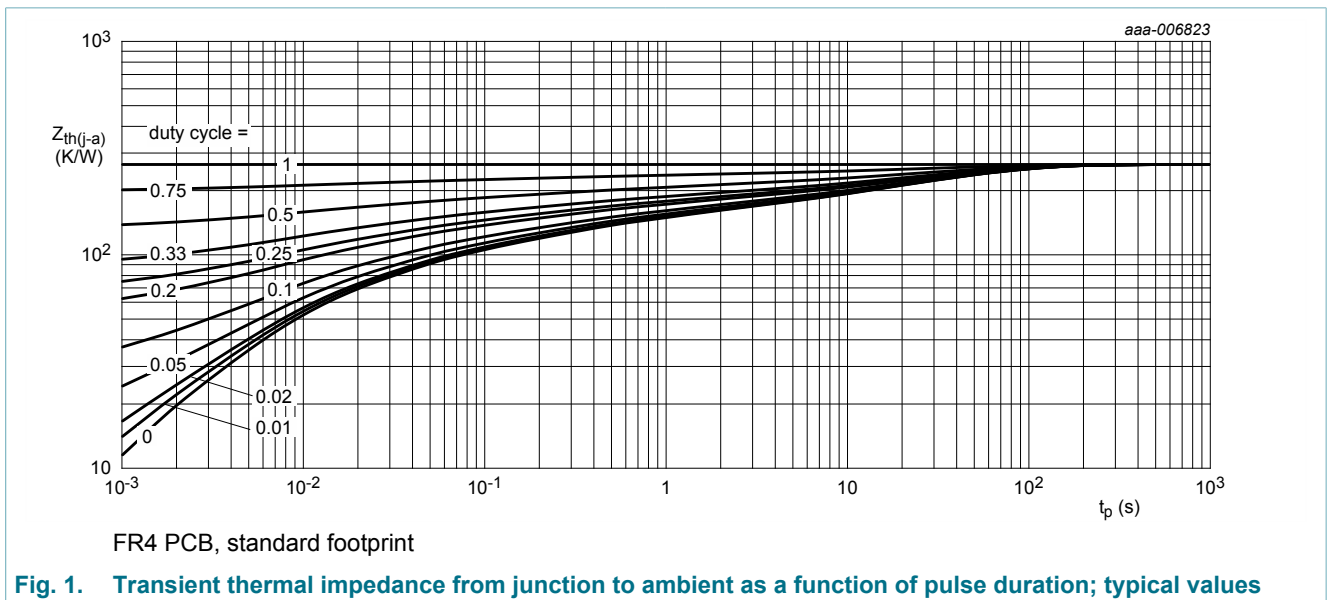
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm<sup>2</sup> each.

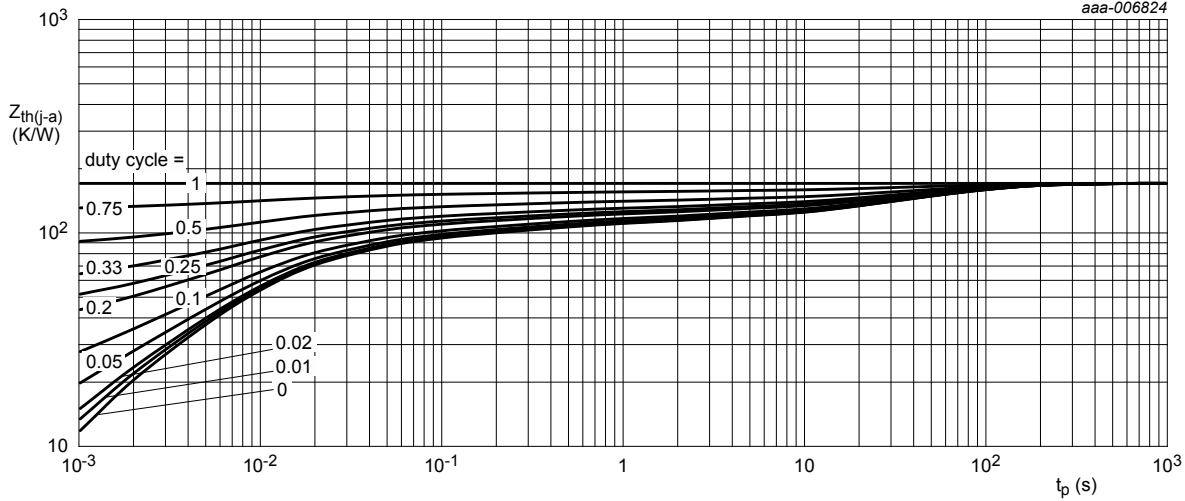
## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	310	K/W
			[1] [3]	-	-	190	K/W
			[1] [4]	-	-	105	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	40	K/W

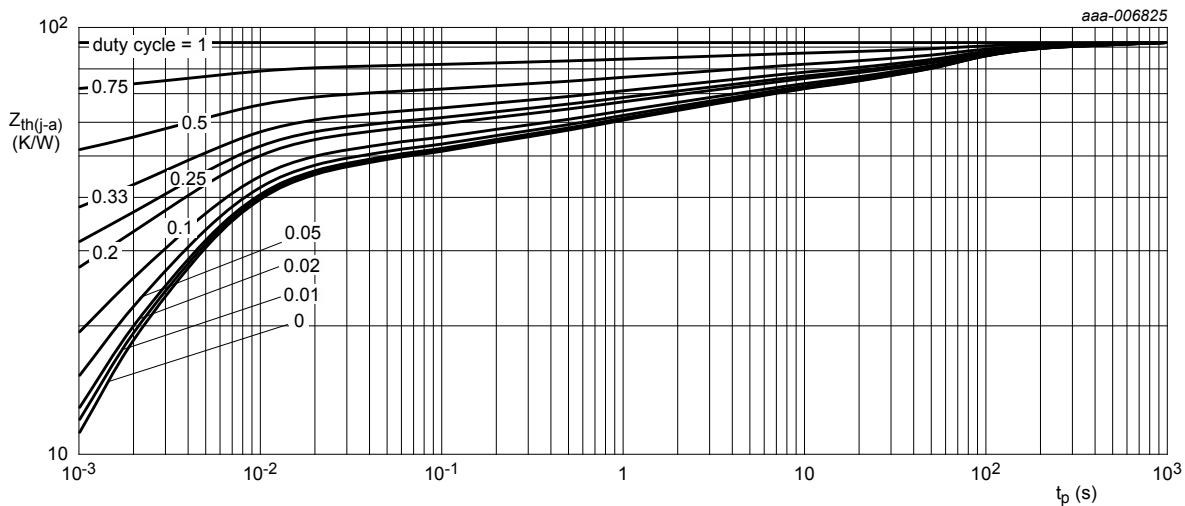
- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm<sup>2</sup> each.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of anode tab.





FR4 PCB, mounting pad for anode and cathode 1 cm<sup>2</sup> each

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

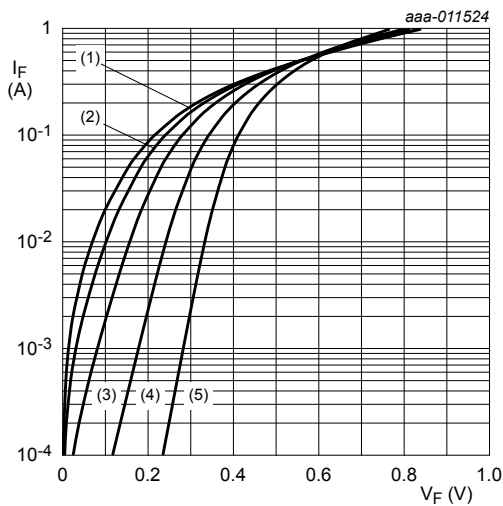
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

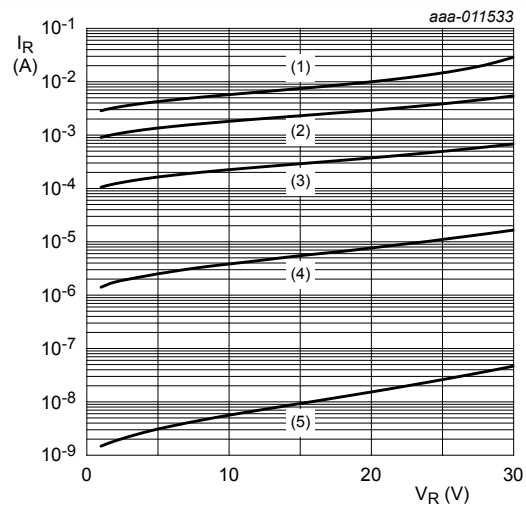
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)R}$	reverse reverse breakdown voltage	$I_R = 100 \mu\text{A}$ ; $t_p = 300 \mu\text{s}$ ; $\delta = 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$	30	-	-	V
$V_F$	forward voltage	$I_F = 0.1 \text{ mA}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$	-	120	185	mV
		$I_F = 1 \text{ mA}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$	-	180	245	mV
		$I_F = 10 \text{ mA}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$	-	250	320	mV

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		$I_F = 100 \text{ mA}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02 ; T_j = 25 \text{ } ^\circ\text{C}$	-	350	410	mV
		$I_F = 200 \text{ mA}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02 ; T_j = 25 \text{ } ^\circ\text{C}$	-	405	470	mV
$I_R$	reverse current	$V_R = 10 \text{ V}; T_j = 25 \text{ } ^\circ\text{C}; \text{pulsed}$	-	4	30	$\mu\text{A}$
		$V_R = 30 \text{ V}; T_j = 25 \text{ } ^\circ\text{C}; \text{pulsed}$	-	20	80	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ } ^\circ\text{C}$	-	22	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ } ^\circ\text{C}$	-	8	-	pF
$t_{rr}$	reverse recovery time	$I_F = 500 \text{ mA}; I_R = 500 \text{ mA}; I_{R(\text{meas})} = 100 \text{ mA}; T_j = 25 \text{ } ^\circ\text{C}$	-	1.37	-	ns



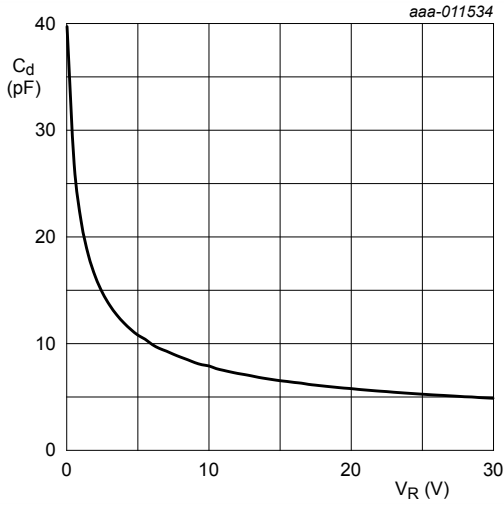
pulsed condition  
 (1)  $T_j = 150 \text{ } ^\circ\text{C}$   
 (2)  $T_j = 125 \text{ } ^\circ\text{C}$   
 (3)  $T_j = 85 \text{ } ^\circ\text{C}$   
 (4)  $T_j = 25 \text{ } ^\circ\text{C}$   
 (5)  $T_j = -40 \text{ } ^\circ\text{C}$

**Fig. 4. Forward current as a function of forward voltage; typical values**



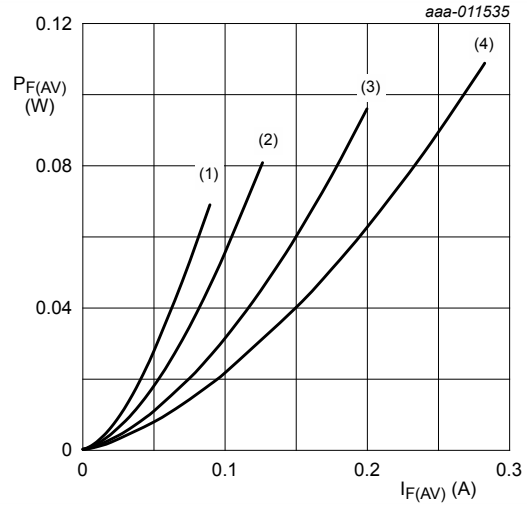
pulsed condition  
 (1)  $T_j = 150 \text{ } ^\circ\text{C}$   
 (2)  $T_j = 125 \text{ } ^\circ\text{C}$   
 (3)  $T_j = 85 \text{ } ^\circ\text{C}$   
 (4)  $T_j = 25 \text{ } ^\circ\text{C}$   
 (5)  $T_j = -40 \text{ } ^\circ\text{C}$

**Fig. 5. Reverse current as a function of reverse voltage; typical values**



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

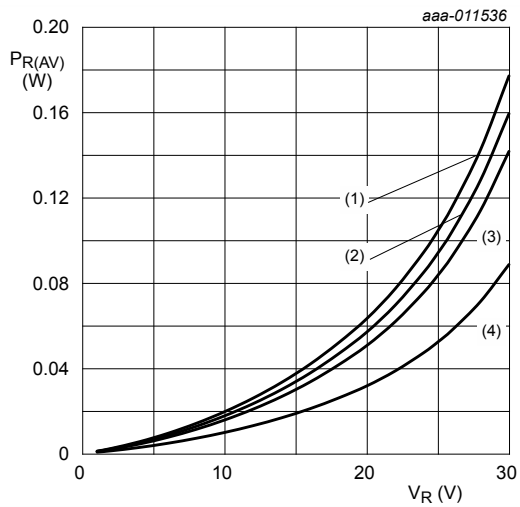
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

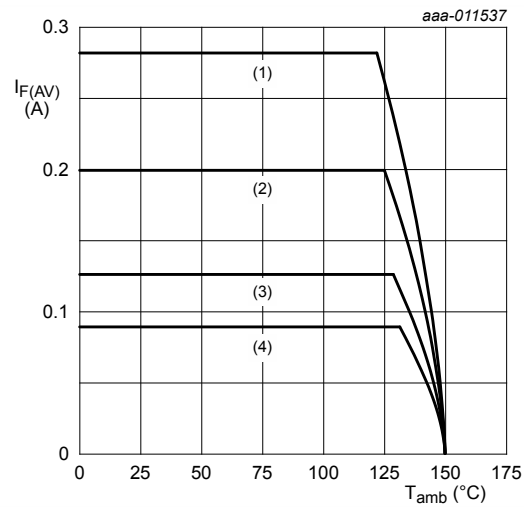
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**

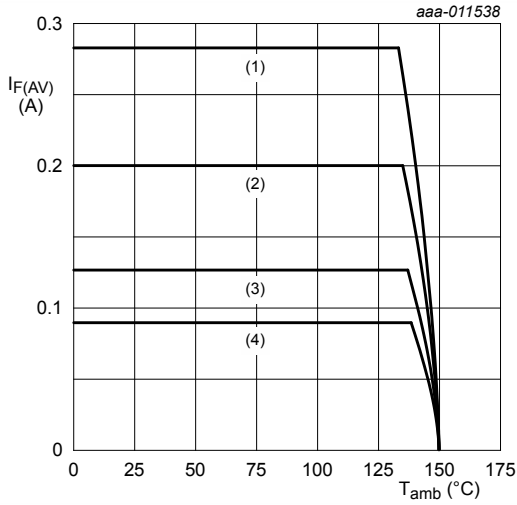


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

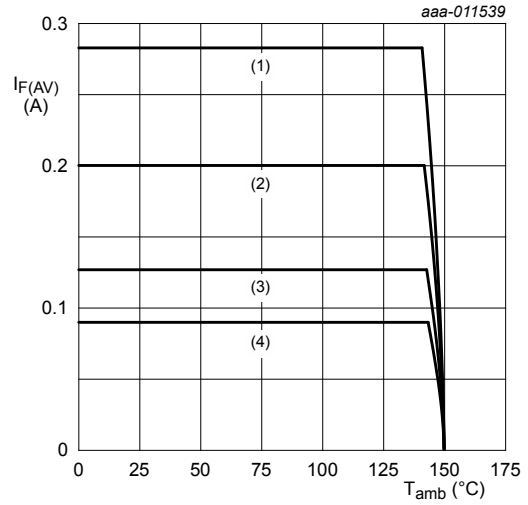
- (1)  $\delta = 1; \text{DC}$
- (2)  $\delta = 0.5; f = 20 \text{ kHz}$
- (3)  $\delta = 0.2; f = 20 \text{ kHz}$
- (4)  $\delta = 0.1; f = 20 \text{ kHz}$

**Fig. 9. Average forward current as a function of ambient temperature; typical values**



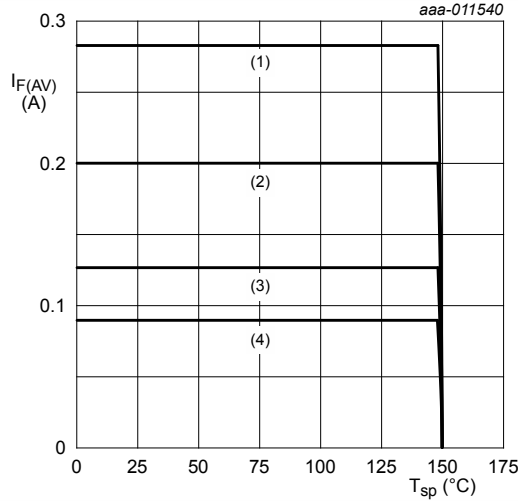
FR4 PCB, mounting pad for anode and cathode 1 cm<sup>2</sup> each  
 T<sub>j</sub> = 150 °C  
 (1) δ = 1; DC  
 (2) δ = 0.5; f = 20 kHz  
 (3) δ = 0.2; f = 20 kHz  
 (4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 T<sub>j</sub> = 150 °C  
 (1) δ = 1; DC  
 (2) δ = 0.5; f = 20 kHz  
 (3) δ = 0.2; f = 20 kHz  
 (4) δ = 0.1; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



T<sub>j</sub> = 150 °C  
 (1) δ = 1; DC  
 (2) δ = 0.5; f = 20 kHz  
 (3) δ = 0.2; f = 20 kHz  
 (4) δ = 0.1; f = 20 kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

### 11. Test information

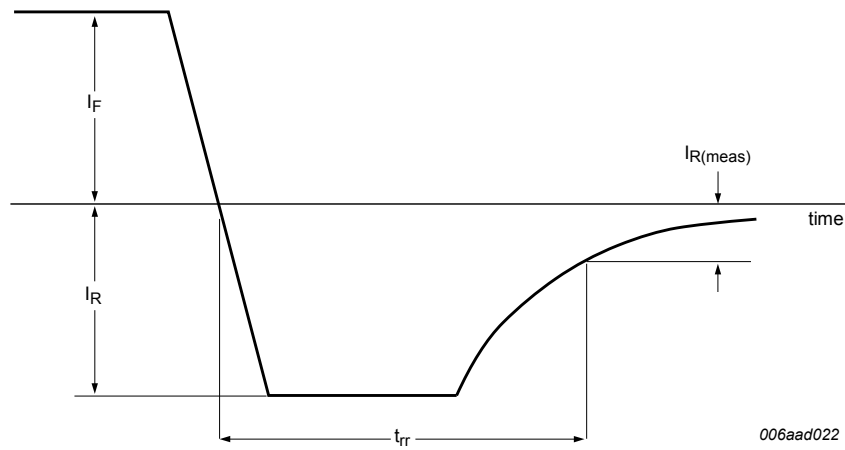


Fig. 13. Reverse recovery definition

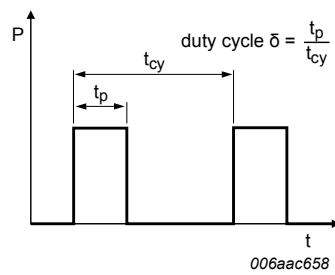


Fig. 14. Duty cycle definition

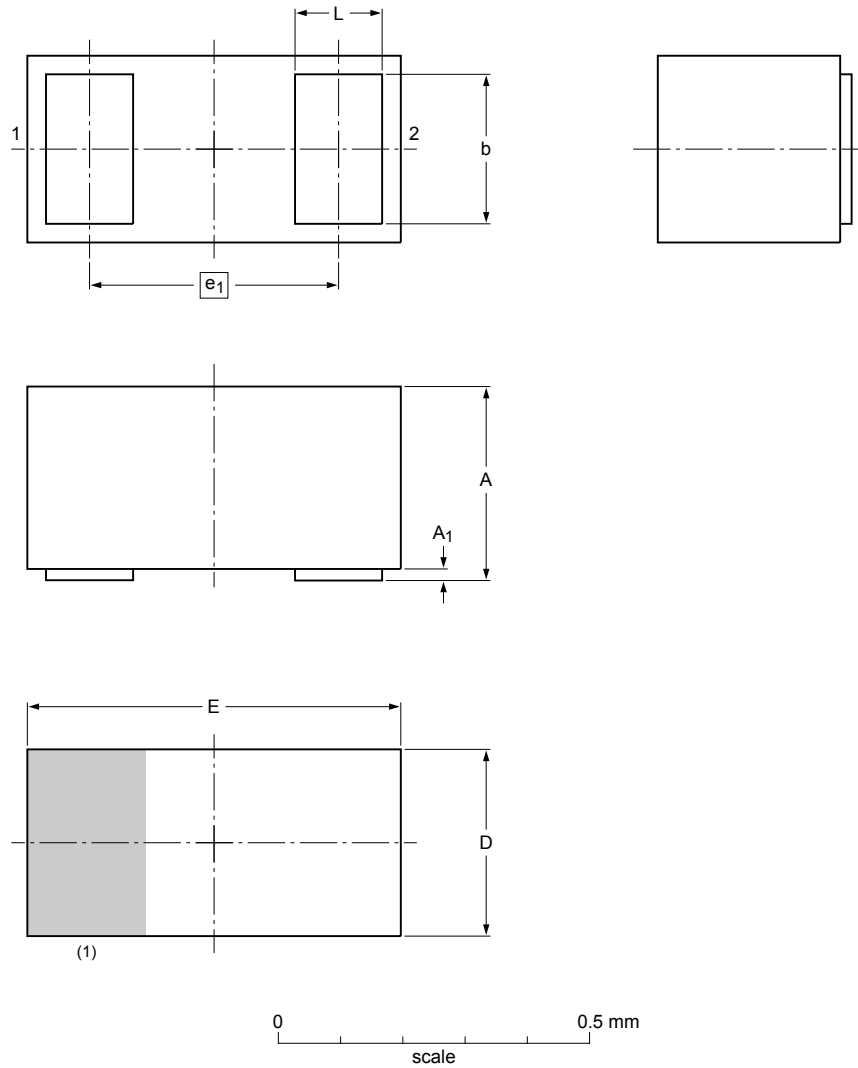
The current ratings for the typical waveforms are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.



## 12. Package outline

Leadless ultra small package; 2 terminals; body 0.6 x 0.3 x 0.3 mm

SOD962-2



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	D	E	e <sub>1</sub>	L
mm	max	0.32	0.03	0.25	0.325	0.625	0.15
	nom					0.4	
	min	0.28		0.23	0.275	0.575	0.13

Note

1. The marking bar indicates the cathode.

sod962-2\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD962-2					-13-07-12- 13-07-17

Fig. 15. Package outline DSN0603-2 (SOD962-2)

### 13. Soldering

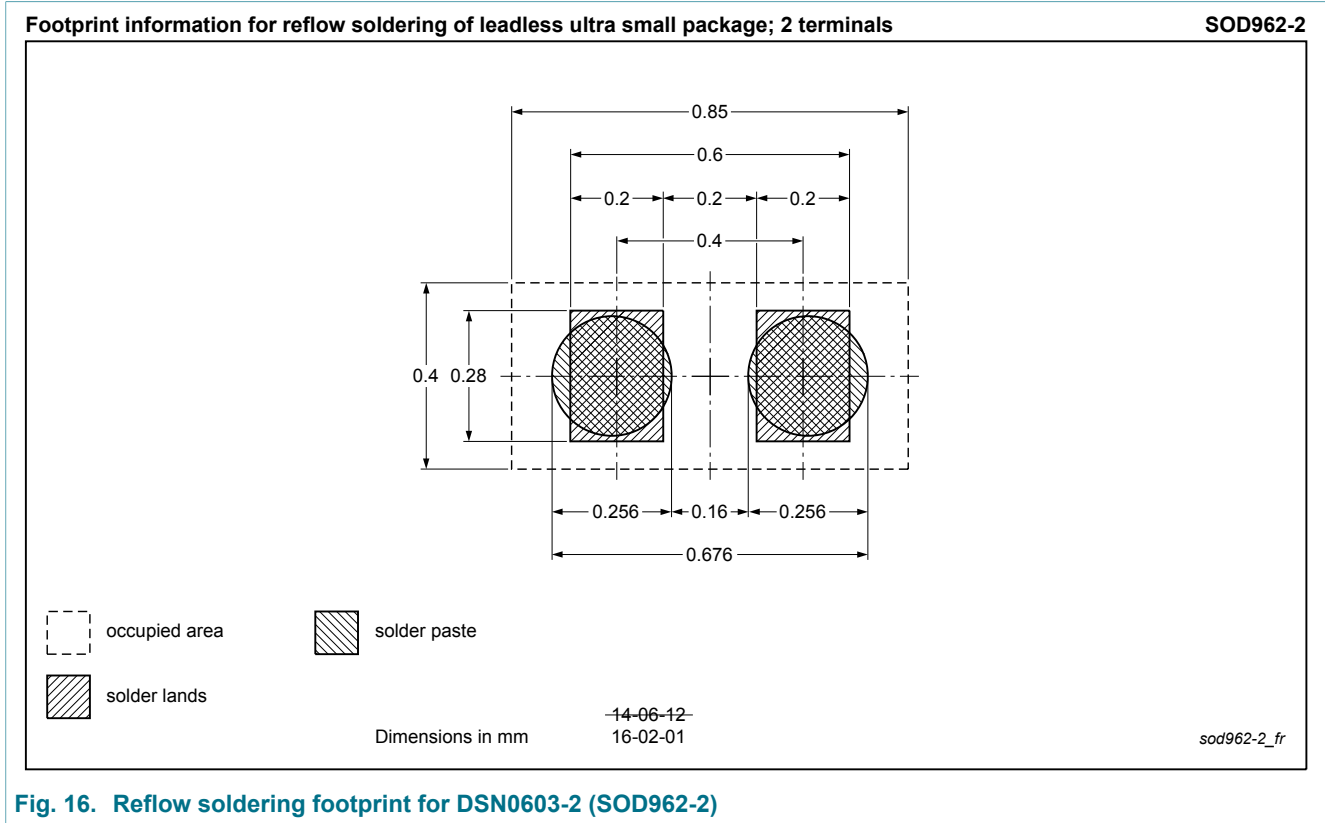


Fig. 16. Reflow soldering footprint for DSN0603-2 (SOD962-2)

### 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3002AESF_S500 v.1	20160517	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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